



StencilWorks™ Understencil Wiping Rolls

The understencil wiping rolls for automatic printers with Vacuum stencil cleaning systems or Regular non-vacuum cleaning systems

StencilWorks™ Understencil Wiping Rolls are used to remove residual solder paste from the bottom side of PC Board stencils. Frequent wiping with StencilWorks Understencil Wiping Rolls prevents smearing, bridging, and solder balls caused by normal printing of solder paste onto PC Boards. StencilWorks rolls are available in a wide range of sizes to fit popular printer models and are available in two materials, Vacuum grade or Regular, non-vacuum grade, depending on your printer cleaning process.

- See selection guide to determine the type of roll that will fit your printer

StencilWorks™ R

- Low lint • Strong and highly absorbent
- Thicker material resists tears

StencilWorks™ V

- Low lint • Strong and absorbent
- Semi-opaque, light weight material for effective vacuum pull

StencilWorks™ IPA Presaturated Stencil Wipes

The general purpose presaturated wipe for cleaning solder paste off of SMT stencils

StencilWorks™ IPA is a highly effective presaturated wipe for removing solder paste, inks, and other contaminants associated with SMT stencil printing. This product is ideal for touch-up cleaning of automatic printer stencils and cleaning semi-automatic printer stencils during and at the end of production runs.

- Safe for plastics
- Flammable
- Ozone safe; CFC/HCFC
- High absorbency and liquid retention
- Strong; will not tear, shred, unravel or lint
- Holds up to the most rigorous scrubbing sometimes required to remove solder paste from SMT stencil surfaces

SIP100PE 100 wipes per tub

For more information please contact:

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